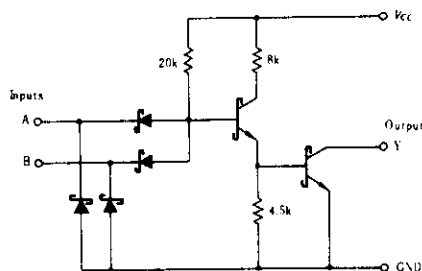
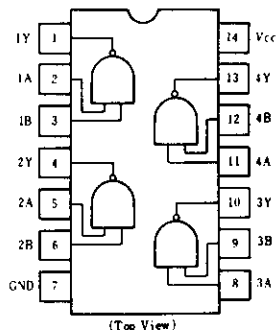


HD74LS01 ● Quadruple 2-input Positive NAND Gates (with Open Collector Outputs)

■ CIRCUIT SCHEMATIC (1/4)



■ PIN ARRANGEMENT



■ RECOMMENDED OPERATING CONDITIONS

Item	Symbol	min	typ	max	Unit
High level output voltage	V_{OH}	—	—	5.5	V
Low level output current	I_{OL}	—	—	8	mA

■ ELECTRICAL CHARACTERISTICS ($T_a = -20 \sim +75^\circ\text{C}$)

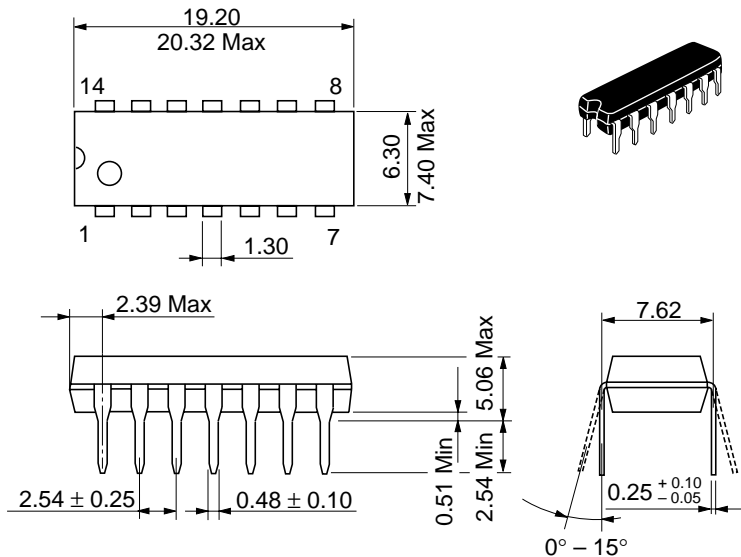
Item	Symbol	Test Conditions	min	typ*	max	Unit	
Input voltage	V_{IH}		2.0	—	—	V	
	V_{IL}		—	—	0.8	V	
Output voltage	V_{OL}	$V_{CC}=4.75\text{V}, V_I=2.7\text{V}$	$I_{OL}=8\text{mA}$	—	—	0.5	V
			$I_{OL}=4\text{mA}$	—	—	0.4	
Input current	I_{IH}	$V_{CC}=5.25\text{V}, V_I=2.7\text{V}$	—	—	2.0	μA	
	I_{IL}	$V_{CC}=5.25\text{V}, V_I=0.4\text{V}$	—	—	-0.4	mA	
	I_I	$V_{CC}=5.25\text{V}, V_I=7\text{V}$	—	—	0.1	mA	
Output current	I_{OH}	$V_{CC}=4.75\text{V}, V_{IL}=0.8\text{V}, V_{OH}=5.5\text{V}$	—	—	100	μA	
Supply current	I_{CCH}	$V_{CC}=5.25\text{V}$	—	0.8	1.6	mA	
	I_{CCL}	$V_{CC}=5.25\text{V}$	—	2.4	4.4	mA	
Input clamp voltage	V_{IK}	$V_{CC}=4.75\text{V}, I_{IN}=-18\text{mA}$	—	—	-1.5	V	

* $V_{CC}=5\text{V}, T_a=25^\circ\text{C}$

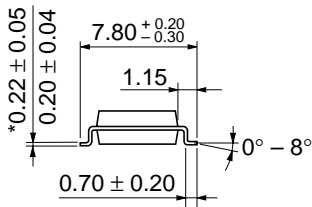
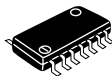
■ SWITCHING CHARACTERISTICS ($V_{CC}=5\text{V}, T_a=25^\circ\text{C}$)

Item	Symbol	Test Conditions	min	typ	max	Unit
Propagation delay time	t_{PLH}	$C_L=15\text{pF}, R_L=2\text{k}\Omega$	—	17	32	ns
	t_{PHL}		—	15	28	ns

Note) Refer to Test Circuit and Waveform of the Common Item



Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.97 g



Hitachi Code	FP-14DA
JEDEC	—
EIAJ	Conforms
Weight (reference value)	0.23 g

*Dimension including the plating thickness
Base material dimension



Hitachi Code	FP-14DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.13 g

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HITACHI

Hitachi, Ltd.

Semiconductor & Integrated Circuits.
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan
Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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For further information write to:

Hitachi Semiconductor
(America) Inc.
179 East Tasman Drive,
San Jose, CA 95134
Tel: <1> (408) 433-1990
Fax: <1> (408) 433-0223

Hitachi Europe GmbH
Electronic components Group
Dornacher Straße 3
D-85622 Feldkirchen, Munich
Germany
Tel: <49> (89) 9 9180-0
Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd.
Electronic Components Group.
Whitebrook Park
Lower Cookham Road
Maidenhead
Berkshire SL6 8YA, United Kingdom
Tel: <44> (1628) 585000
Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd.
16 Collyer Quay #20-00
Hitachi Tower
Singapore 049318
Tel: 535-2100
Fax: 535-1533

Hitachi Asia Ltd.
Taipei Branch Office
3F, Hung Kuo Building, No.167,
Tun-Hwa North Road, Taipei (105)
Tel: <886> (2) 2718-3666
Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7/F., North Tower, World Finance Centre,
Harbour City, Canton Road, Tsim Sha Tsui,
Kowloon, Hong Kong
Tel: <852> (2) 735 9218
Fax: <852> (2) 730 0281
Telex: 40815 HITEC HX

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